

DATA SHEET

SKY77517-21 TX-RX iPAC™ FEM for Dual-Band GSM/GPRS


Applications

- Dual-band cellular handsets encompassing
 - Class 4 GSM850
 - PCS1900
 - Class 12 GPRS multi-slot operation

Features

- High efficiency
 - GSM850 48%
 - PCS 41%
- Low transmit supply current
 - GSM850 1.26 A
 - PCS1900 0.9 A
- Internal ICC sense resistor for iPAC
- Closed loop iPAC
- 50 Ω matched Input/Output
- TX-VCO-to-antenna and antenna-to-RX-SAW filter RF interface
- TX harmonics below -33 dBm
- PHEMT RF switches afford high linearity, low insertion loss, and less than 20 μA supply current in receive modes
- Small outline: 6 mm x 8 mm
- Low profile: 1.2 mm
- Compatible with multiple logic families
- Low APC current: 25 μA

NEW Skyworks offers lead (Pb)-free, RoHS (Restriction of Hazardous Substances)-compliant packaging.



Description

The SKY77517-21 is a transmit and receive front-end module (FEM) with Integrated Power Amplifier Control (iPAC™) for dual-band cellular handsets comprising GSM850 and PCS1900 operation. Designed in a low profile, compact form factor, the SKY77517-21 offers a complete Transmit VCO-to-Antenna and Antenna-to-Receive SAW filter solution. The FEM also supports Class 12 General Packet Radio Service (GPRS) multi-slot operation.

The module consists of a GSM850 PA block and a PCS1900 PA block, impedance-matching circuitry for 50 Ω input and output impedances, TX harmonics filtering, high linearity and low insertion loss PHEMT RF switches, diplexer and a Power Amplifier Control (PAC) block with internal current sense resistor. A custom BiCMOS integrated circuit provides the internal PAC function and decoder circuitry to control the RF switches. The two Heterojunction Bipolar Transistor (HBT) PA blocks are fabricated onto a single Gallium Arsenide (GaAs) die. One PA block supports the GSM850 band and the other PA block supports the PCS1900 band. Both PA blocks share common power supply pads to distribute current. The output of each PA block and the outputs to the two receive pads are connected to the antenna pad through PHEMT RF switches and a diplexer. The GaAs die, PHEMT die, Silicon (Si) die and passive components are mounted on a multi-layer laminate substrate. The assembly is encapsulated with plastic overmold.

Band selection and control of transmit and receive modes are performed using two external control pads. Refer to the functional block diagram in Figure 1 below. The band select pad (BS) selects between GSM and PCS modes of operation. The transmit enable (TX_EN) pad controls receive or transmit mode of the respective RF switch (TX = logic 1). Proper timing between transmit enable (TX_EN) and Analog Power Control (VRAMP) allows for high isolation between the antenna and TX-VCO while the VCO is being tuned prior to the transmit burst.

The SKY77517 is compatible with logic levels from 1.2 V to VCC for BS and TX_EN pads, depending on the level applied to the VLOGIC pad. This feature provides additional flexibility for the designer in the selection of FEM interface control logic.

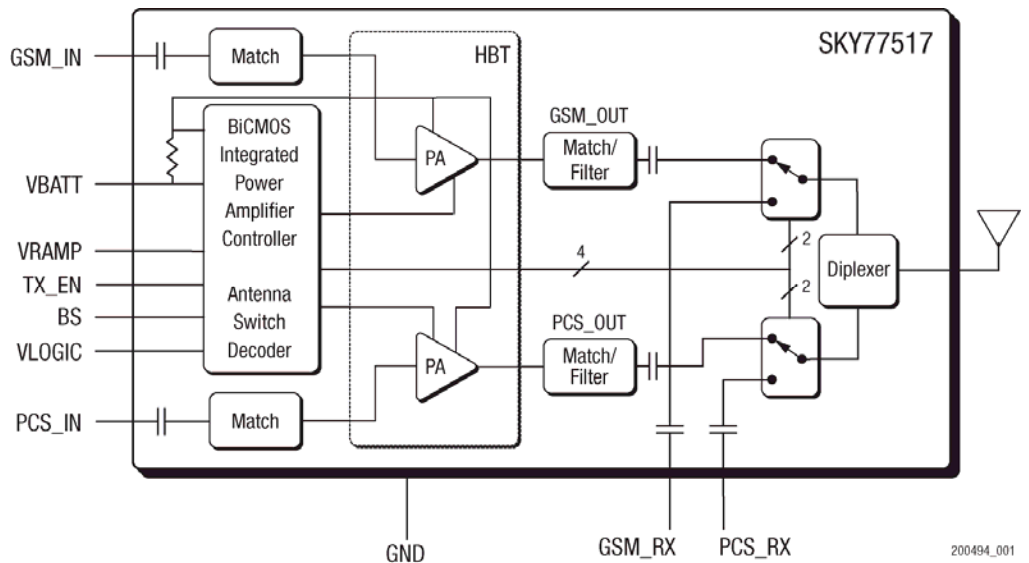


Figure 1. Functional Block Diagram

Electrical Specifications

The following tables list the electrical characteristics of the SKY77517-21 Front-End Module. The absolute maximum ratings and recommended operating conditions for the SKY77517-21 are listed in Table 1 and Table 2, respectively. Table 3 specifies the mode control logic and Table 4 contains the electrical characteristics of the SKY77517-21 for modes GSM850 and

PCS1900. Figure 2 presents an application schematic for the SKY77517-21.

The SKY77517-21 is a static-sensitive electronic device and should not be stored or operated near strong electrostatic fields. Detailed information on device dimensions, pad descriptions, packaging and handling can be found in later sections of this data sheet.

Table 1. Absolute Maximum Ratings

Parameter	Minimum	Maximum	Unit
Input Power (P _{IN})	—	15	dBm
Supply Voltage (V _{CC}), Standby V _{RAMP} ≤ 0.3 V V _{LOGIC} ≤ 0.5 V	—	7	V
Control Voltage (V _{RAMP})	-0.5	V _{CC_MAX} - 0.2 V (See Table 4)	V
Storage Temperature	-55	150	°C

Table 2. Recommended Operating Conditions

Parameter	Minimum	Typical	Maximum	Unit
Supply Voltage (V _{CC})	2.7	3.3	4.8	V
Supply Current (I _{CC})	0		1.8	A
Operating Case Temperature (T _{CASE}) ¹ 1-Slot (12.5% duty cycle)	-20		85	°C
2-Slot (25% duty cycle)	-20		85	

¹ Case Operating Temperature refers to the temperature of the GROUND PAD on the underside of the package.

Table 3. SKY77517-21 Mode Control Logic

Mode	V _{LOGIC}	Input Control Bits	
		TX_En	BS
STANDBY	0	X ¹	X ¹
GSM_RX	1	0	0
PCS_RX	1	0	1
GSM_TX	1	1	0
PCS_TX	1	1	1

¹ X = don't care

Table 4. SKY77517–21 Electrical Specifications¹ (1 of 5)

General							
Parameter	Symbol	Test Condition	Minimum	Typical	Maximum	Units	
Supply voltage	VCC	—	2.7	3.3	4.8	V	
Power control impedance	ZVRAMP	—		300		kΩ	
VLOGIC control voltage	LOW	VLOGIC_LOW	—	–0.1	—	0.5	V
	HIGH	VLOGIC_HIGH		1.2	—	VCC	
VLOGIC current	I _{VLOGIC}	VLOGIC ≤ 2.7 V TX_EN ≤ 0.4 V BS ≤ 0.4 V	—	1	20	μA	
Band Select control voltage	LOW	VBS_LOW	—	–0.1	—	30% VLOGIC	V
	HIGH	VBS_HIGH		70% VLOGIC	—	VLOGIC	
Band Select current	I _{BS}	BS ≤ 2.7 V	—	8	20	μA	
TX_EN control voltage	LOW	V _{TX_EN_LOW}	—	–0.1	—	30% VLOGIC	V
	HIGH	V _{TX_EN_HIGH}		70% VLOGIC	—	VLOGIC	
TX_EN current	I _{TX_EN}	TX_EN ≤ 2.7 V	—	8	20	μA	
Leakage current	Standby Mode	I _{OS}	—	2	10	μA	
	Receive Mode	I _{QRX}					
		VCC ≤ 4.8 V VLOGIC = VLOGIC_LOW VRAMP ≤ 0.1 V TX_EN ≤ 0.4 V BS ≤ 0.4 V BS ≥ VLOGIC – 0.4 V T _{CASE} = 25 °C PIN ≤ –60 dBm					
		VCC ≤ 4.8 V 1.2 V ≤ VLOGIC ≤ 2.7 V VRAMP ≤ 0.1 V TX_EN ≤ 0.4 V BS ≤ 0.4 V BS ≥ VLOGIC – 0.4 V T _{CASE} = 25 °C PIN ≤ –60 dBm		15	50		

Table 4. SKY77517–21 Electrical Specifications¹ (2 of 5)

GSM850 Mode (f = 824 to 849 MHz and P _{IN} = 0 to 6 dBm)						
Parameter	Symbol	Test Condition	Minimum	Typical	Maximum	Units
Frequency range	f	—	824	—	849	MHz
Input power	P _{IN}	—	0	—	6	dBm
Analog power control voltage	V _{RAMP}	—	0.2	—	1.8	V
Power Added Efficiency	PAE	V _{CC} = 3.3 V P _{OUT} = 33 dBm TX_EN = V _{TX_EN_HIGH} V _{RAMP} set for P _{OUT} = 33 dBm pulse width 577 μs duty cycle 1:8 T _{CASE} = 25 °C	41	48	—	%
Supply Current @ Rated Power	I _{CC_33 dBm}	V _{CC} = 3.3 V P _{IN} = 3 dBm P _{OUT} = 33 dBm TX_EN = V _{TX_EN_HIGH} V _{RAMP} set for P _{OUT} = 33 dBm pulse width 577 μs duty cycle 1:8 T _{CASE} = 25 °C	—	1.26	1.48	A
Supply Current @ Minimum Power	I _{CC_5 dBm}	V _{CC} = 3.3 V P _{IN} = 3 dBm P _{OUT} = 5 dBm TX_EN = V _{TX_EN_HIGH} V _{RAMP} set for P _{OUT} = 5 dBm pulse width 577 μs duty cycle 1:8 T _{CASE} = 25 °C	—	53	60	mA
Harmonics 2nd to 13th	2f ₀ to 13f ₀	BW = 3 MHz 5 dBm ≤ P _{OUT} ≤ 33 dBm V _{RAMP} controlled ⁶	—	-40	-33	dBm
Output power	P _{OUT}	V _{CC} = 3.3 V T _{CASE} = 25 °C P _{IN} = 0 dBm	33.0	33.7	—	dBm
	P _{OUT_MAX LOW VOLTAGE}	V _{CC} = 2.7 V TX_EN = V _{TX_EN_HIGH} T _{CASE} = -20 °C to 85 °C P _{IN} = 0 dBm	30.5	32.2	—	
	P _{OUT_MAX HIGH VOLTAGE}	V _{CC} = 4.8 V TX_EN = V _{TX_EN_HIGH} T _{CASE} = -20 °C to 85 °C P _{IN} = 0 dBm	30.5	34.5	—	
Input VSWR	Γ _{IN}	P _{OUT} = 5 to 33 dBm V _{RAMP} controlled ⁶	—	1.5:1	2.5:1	
Forward isolation ⁴	P _{OUT_RX}	P _{IN} = 6 dBm V _{RAMP} ≤ 0.1 V V _{LOGIC} = V _{LOGIC_HIGH} TX_EN = V _{TX_EN_LOW} Mode = GSM_RX (see Table 3)	—	-55	-45	dBm
	P _{OUT_ENABLED_TX}	P _{IN} = 6 dBm V _{RAMP} ≤ 0.1 V V _{LOGIC} = V _{LOGIC_HIGH} TX_EN = V _{TX_EN_HIGH} Mode = GSM_TX (see Table 3)	—	-25	-5	
Coupling of GSM850 TX output (f ₀) to GSM_RX output pad ⁴	CGHI_TX-RX_F0	5 dBm ≤ P _{OUT} ≤ 33 dBm Mode = GSM_TX (see Table 3)	—	3	11	dBm
Coupling of GSM850 TX output (2f ₀ , 3f ₀) to PCS_RX output pad ⁴	CGHI_TX-PCS_RX	5 dBm ≤ P _{OUT} ≤ 33 dBm Mode = GSM_TX (see Table 3)	—	-45	-36	dBm

Table 4. SKY77517-21 Electrical Specifications¹ (3 of 5)

GSM850 Mode (f = 824 to 849 MHz and P _{IN} = 0 to 6 dBm) [continued]						
Parameter	Symbol	Test Condition	Minimum	Typical	Maximum	Units
Spurious	Spur	All combinations of the following parameters: V _{RAMP} = controlled ² P _{IN} = min. to max. V _{CC} = 2.7 V to 4.8 V Load VSWR = 12:1, all phase angles	No parasitic oscillation > -36 dBm			
Load mismatch	Load	All combinations of the following parameters: V _{RAMP} = controlled ² P _{IN} = min. to max. V _{CC} = 2.7 V to 4.8 V Load VSWR = 20:1, all phase angles	No module damage or permanent degradation			
RX Band Spurious	RX_SPUR	At f ₀ + 20 MHz (869 to 894 MHz) RBW = 100 kHz V _{CC} = 3.3 V 5 dBm ≤ P _{OUT} ≤ 33 dBm T _{CASE} = 25 °C	—	-84	-83	dBm
		At 1930 to 1990 MHz RBW = 100 kHz V _{CC} = 3.3 V T _{CASE} = 25 °C 5 dBm ≤ P _{OUT} ≤ 33 dBm	—	-101	-84	
Power control dynamic range	PC _{DR}		30	50	—	dB
Power control variation	PC _V	Control level 5-15 (V _{CC} ≥ 3.3 V) P _{OUT} 13 to 33 dBm T _{CASE} = 25 °C	-1.0	—	1.0	dB
		P _{OUT} 13 to 33 dBm	-1.5	—	1.5	
		Control level 16-19 P _{OUT} 5 to 11 dBm T _{CASE} = 25 °C	-2.0	—	2.0	
		P _{OUT} 5 to 11 dBm	-3.5	—	3.5	
Power control slope	PC _S	5 to 33 dBm	—	—	150	dB/V
GSM850 RECEIVE (f = 869 to 894 MHz) Mode = GSM_RX						
Parameter	Symbol	Test Condition	Minimum	Typical	Maximum	Units
Frequency range	f	—	869	—	894	MHz
Insertion Loss, ANT to GSM_RX ⁴	IL GSM_RX	—	—	1.0	1.3	dB
VSWR ANT, GSM_RX ⁴	Γ _{IN} , Γ _{OUT}	—	—	1.2:1	1.5:1	

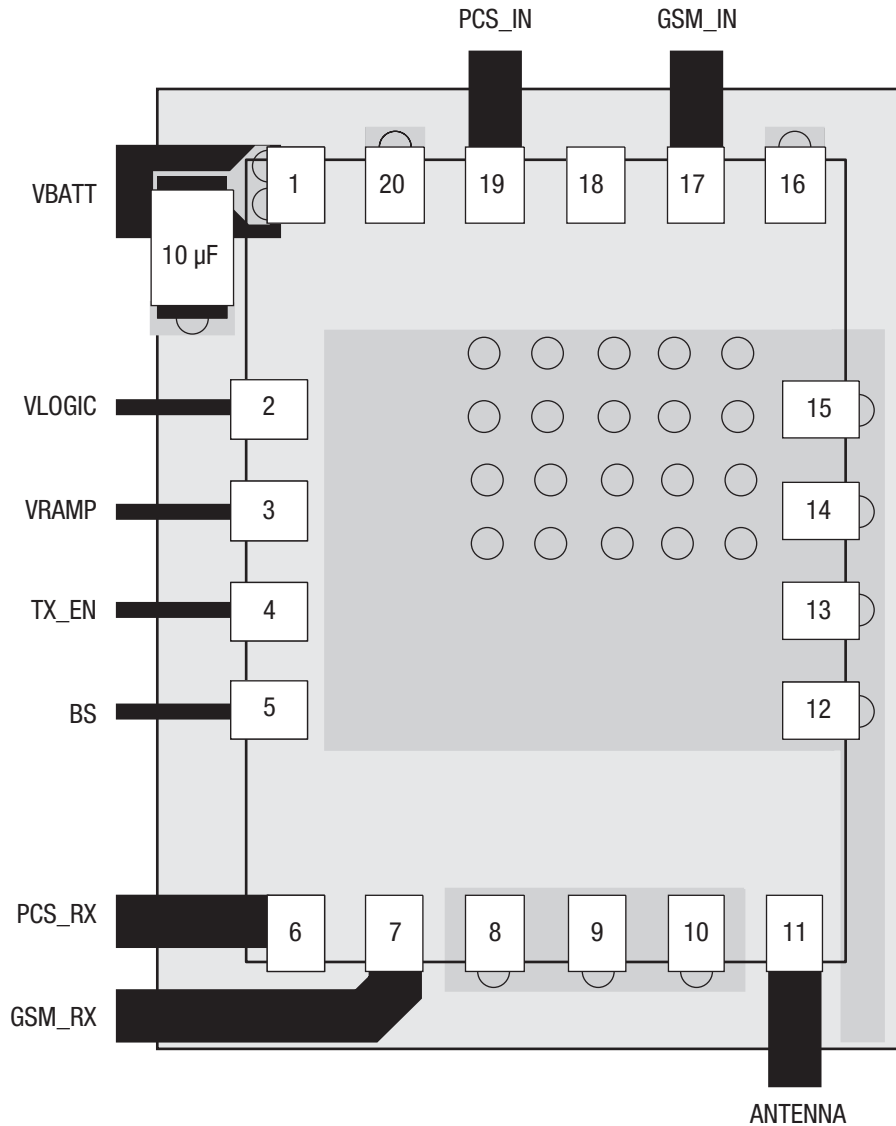
Table 4. SKY77517-21 Electrical Specifications¹ (4 of 5)

PCS1900 Mode (f = 1850 to 1910 MHz and P _{IN} = 0 to 6 dBm)							
Parameter	Symbol	Test Condition	Minimum	Typical	Maximum	Units	
Frequency range	f	—	1850	—	1910	MHz	
Input power	P _{IN}	—	0	—	6	dBm	
Analog power control voltage	V _{RAMP}	—	0.2	—	1.8	V	
Power Added Efficiency	PAE	V _{CC} = 3.3 V P _{OUT} = 31 dBm TX_EN = V _{TX_EN_HIGH} V _{RAMP} set for P _{OUT} = 31 dBm pulse width 577 μs duty cycle 1:8 T _{CASE} = 25 °C	35	41	—	%	
Supply Current @ Rated Power	I _{cc_31 dBm}	V _{CC} = 3.3 V P _{IN} = 3 dBm P _{OUT} = 31 dBm TX_EN = V _{TX_EN_HIGH} V _{RAMP} set for P _{OUT} = 31 dBm pulse width 577 μs duty cycle 1:8 T _{CASE} = 25 °C	—	0.93	1.04	A	
Supply Current @ Minimum Power	I _{cc_0 dBm}	V _{CC} = 3.3 V P _{IN} = 3 dBm P _{OUT} = 0 dBm TX_EN = V _{TX_EN_HIGH} V _{RAMP} set for P _{OUT} = 0 dBm pulse width 577 μs duty cycle 1:8 T _{CASE} = 25 °C	—	45	55	mA	
Harmonics	2 nd , 6 th to 7 th	2fo, 6fo to 7fo	BW = 3 MHz, 0 dBm ≤ P _{OUT} ≤ 31 dBm V _{RAMP} controlled ⁵	—	-40	-33	dBm
	3 rd	3fo		—	-35	-28	
	4 th	4fo		—	-35	-30	
	5 th	5fo		—	-30	-25	
Output power	P _{OUT}	V _{CC} = 3.3 V T _{CASE} = 25 °C P _{IN} = 0 dBm	31.0	32.0	—	dBm	
	P _{OUT_MAX LOW VOLTAGE}	V _{CC} = 2.7 V TX_EN = V _{TX_EN_HIGH} T _{CASE} = -20 °C to 85 °C P _{IN} = 0 dBm	28.5	30.0	—		
	P _{OUT_MAX HIGH VOLTAGE}	V _{CC} = 4.8 V TX_EN = V _{TX_EN_HIGH} T _{CASE} = -20 °C to 85 °C P _{IN} = 0 dBm	28.5	32.5	—		
Input VSWR	Γ _{IN}	P _{OUT} = 0 to 31 dBm V _{RAMP} controlled ⁵	—	1.5:1	2.5:1	—	
Forward isolation ⁴	P _{OUT_RX}	P _{IN} = 6 dBm V _{RAMP} ≤ 0.1 V V _{LOGIC} = V _{TX_EN_HIGH} TX_EN = V _{TX_EN_LOW} Mode=PCS_RX (see Table 3)	—	-60	-53	dBm	
	P _{OUT_ENABLED_TX}	P _{IN} = 6 dBm V _{RAMP} ≤ 0.1 V V _{LOGIC} = V _{LOGIC_HIGH} TX_EN = V _{TX_EN_HIGH} Mode = PCS_TX (see Table 3)	—	-35	-5		
Coupling of PCS TX output to Receive RF output pad ⁴	CPCS_TX-RX_F0	0 dBm ≤ P _{OUT} ≤ 31 dBm Mode = PCS_TX (see Table 3)	—	2	9	dBm	

Table 4. SKY77517-21 Electrical Specifications¹ (5 of 5)

PCS1900 Mode (f = 1850 to 1910 MHz and PIN = 0 to 6 dBm) [continued]						
Parameter	Symbol	Test Condition	Minimum	Typical	Maximum	Units
Spurious	Spur	All combinations of the following parameters: VRAMP = controlled ³ PIN = min. to max VCC = 2.7 V to 4.8 V Load VSWR = 12:1, all phase angles	No parasitic oscillation > -36 dBm			
Load mismatch	Load	All combinations of the following parameters: VRAMP = controlled ³ PIN = min. to max. VCC = 2.7 V to 4.8 V Load VSWR = 20:1, all phase angles	No module damage or permanent degradation			
RX Band Spurious	RX_SPUR	At f ₀ + 20 MHz (1930 to 1990 MHz) RBW = 100 kHz VCC = 3.3 V TCASE = 25 °C 0 dBm ≤ P _{OUT} ≤ 31 dBm	—	-83	-78	dBm
		869 to 894 MHz RBW = 100 kHz VCC = 3.3 V TCASE = 25 °C 0 dBm ≤ P _{OUT} ≤ 31 dBm	—	—	-87	
Power control dynamic range	PCDR		35	50	—	dB
Power control variation	PCV	Control level 0-8 VCC ≥ 3.3 V P _{OUT} 14 to 30 dBm TCASE = 25 °C	-1.5	—	1.5	dB
		P _{OUT} 14 to 30 dBm	-2.0	—	2.0	
		Control level 9-13 P _{OUT} 4 to 12 dBm TCASE = 25 °C	-2.5	—	2.5	
		P _{OUT} 4 to 12 dBm	-3.5	—	3.5	
		Control level 14-15 P _{OUT} 0 to 2 dBm TCASE = 25 °C	-3.0	—	3.0	
		P _{OUT} 0 to 2 dBm	-4.5	—	4.5	
Power control slope	PCs	0 to 30 dBm	—	—	150	dB/V
PCS1900 RECEIVE (f = 1930 to 1990 MHz) Mode = PCS_RX						
Parameter	Symbol	Test Condition	Minimum	Typical	Maximum	Units
Frequency range	f	—	1930	—	1990	MHz
Insertion Loss, ANT to PCS_RX ⁴	IL PCS_RX	—	—	1.2	1.5	dB
VSWR ANT, PCS_RX ⁴	Γ _{IN} , Γ _{OUT}	—	—	1.2:1	1.5:1	

¹ Unless specified otherwise:
TCASE = -20 °C to max. operating temperature (see Table 2), RL = 50 Ω, pulsed operation with pulse width ≤ 1154 μs and duty cycle ≤ 2:8, VCC = 2.7 V to 4.8 V.
² ICC = 0A to xA, where x = current at P_{OUT} = 33 dBm, 50 Ω load, and VCC = 3.3 V.
³ ICC = 0A to xA, where x = current at P_{OUT} = 31 dBm, 50 Ω load, and VCC = 3.3 V.
⁴ Terminate all unused RF ports with 50 Ω loads
⁵ Max VRAMP = VRAMP @ P_{OUT} = 31 dBm, 50 Ω load, TCASE 25 °C, PIN = 3 dBm
⁶ Max VRAMP = VRAMP @ P_{OUT} = 33 dBm, 50 Ω load, TCASE 25 °C, PIN = 3 dBm



NOTES:

1. The value of 10 µF cap is dependent on the noise level on the phone board.
2. Ensure sufficient number of vias to supply battery current to Vbatt.
3. VBATT trace width should be ≥ 1 mm.
4. Ground terminal of bypass capacitor connected to ground plane with vias.
5. Layer 2 should be solid ground plane under SKY77517 and any RF trace interconnect.

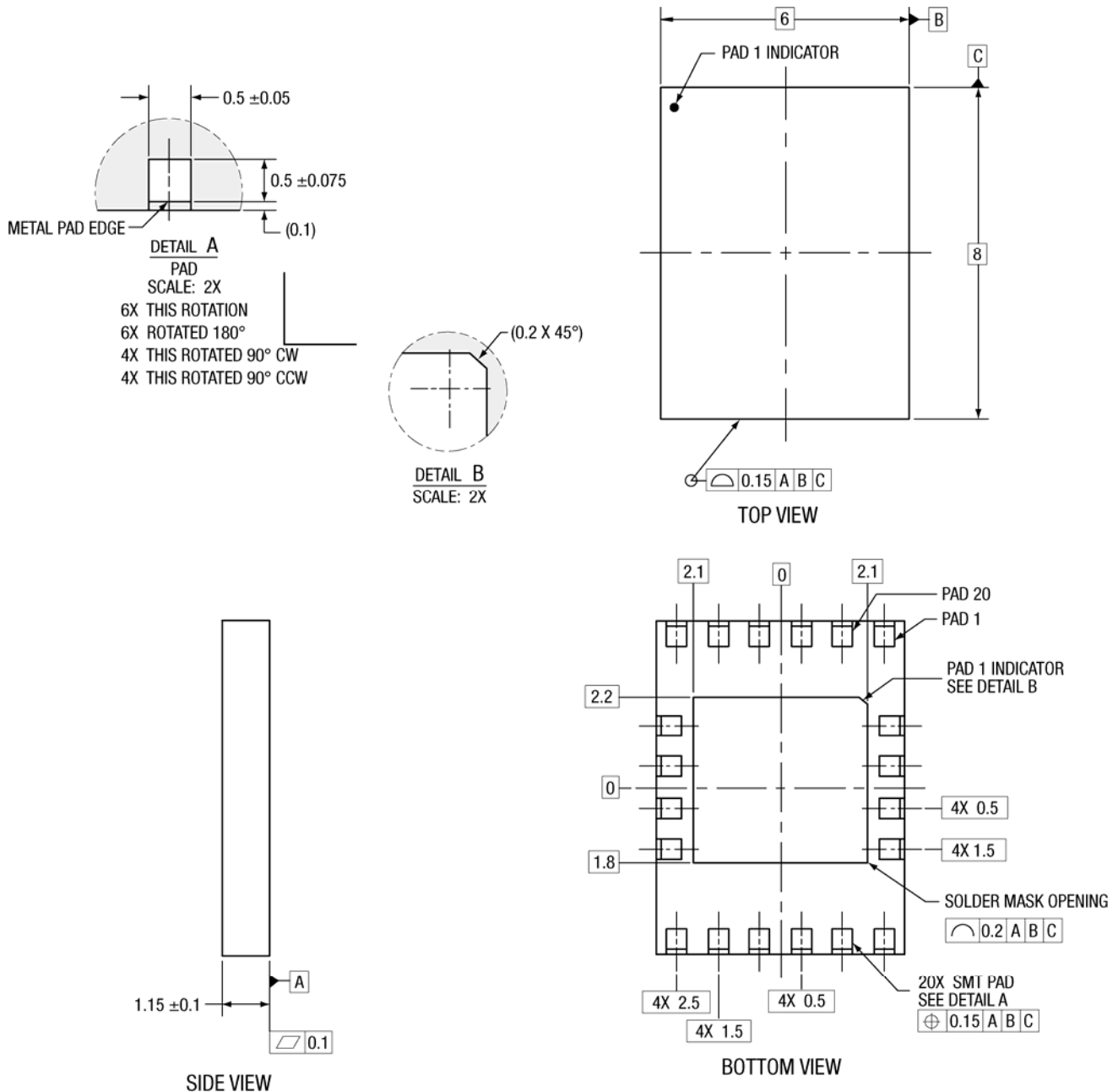
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Figure 2. SKY77517-21 Application Schematic Diagram

Package Dimensions and Pad Descriptions

Figure 3 is a mechanical diagram of the pad layout for the SKY77517-21, a 20-pad leadless dual-band FEM. Figure 4 provides a recommended phone board layout footprint for the FEM to help the designer attain optimum thermal conductivity, good grounding, and minimum RF discontinuity for the 50-ohm

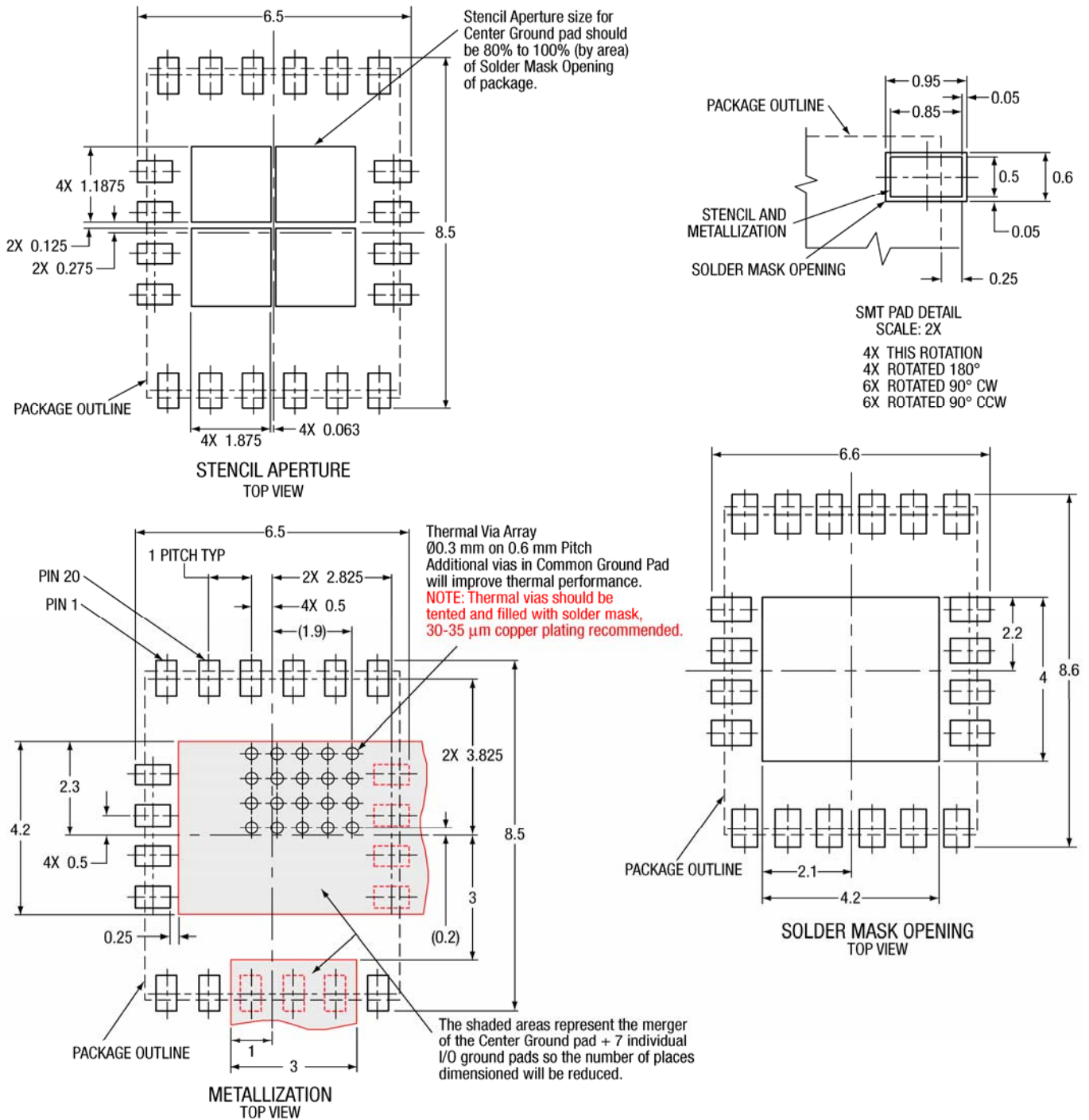
terminals. Figure 5 illustrates the device pad configuration and the numbering convention which starts with pad 1 at the upper left as indicated, and increments counter-clockwise around the package. Table 5 lists the pad names and the associated signal descriptions. Figure 6 interprets typical case markings.



- NOTES: UNLESS OTHERWISE SPECIFIED.
1. Dimensioning and Tolerancing in accordance with ASME Y14.5-1994.
 2. Pads are solder mask defined on 3 edges.
 3. All dimensions are in millimeters.

Figure 3. SKY77517-21 FEM Package Dimensions - 20-Pad Leadless (All Views)

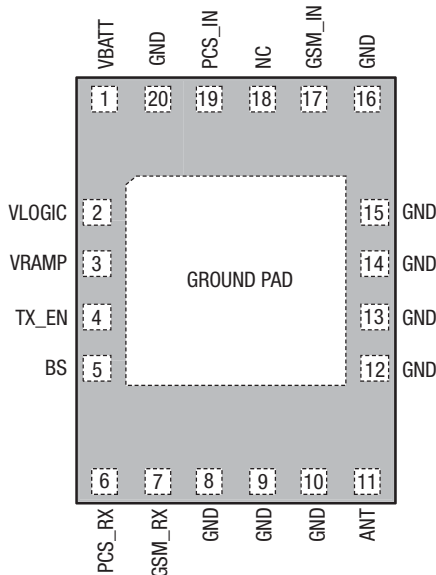
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All dimensions are in millimeters.

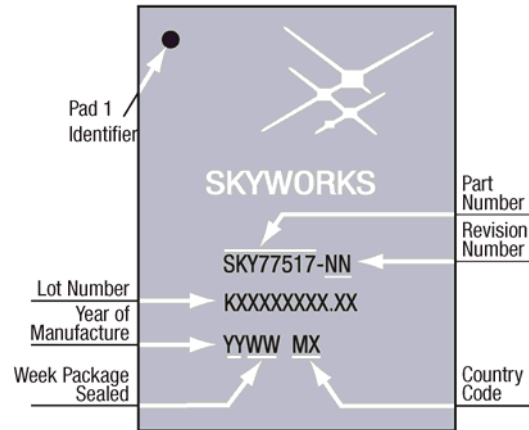
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Figure 4. Phone PCB Layout Footprint for 6 x 8 mm, 20-Pad Package with Grid-Bottom Solder Mask – SKY77517-21 Specific



Pad layout as seen from top view looking through the package. 200494_005

Figure 5. SKY77517-21 FEM Package Pad Configuration – 20-Pad Leadless (Top View)



200472_006

Figure 6. Typical Case Markings

Table 5. SKY77517-21 Pad Names and Signal Descriptions

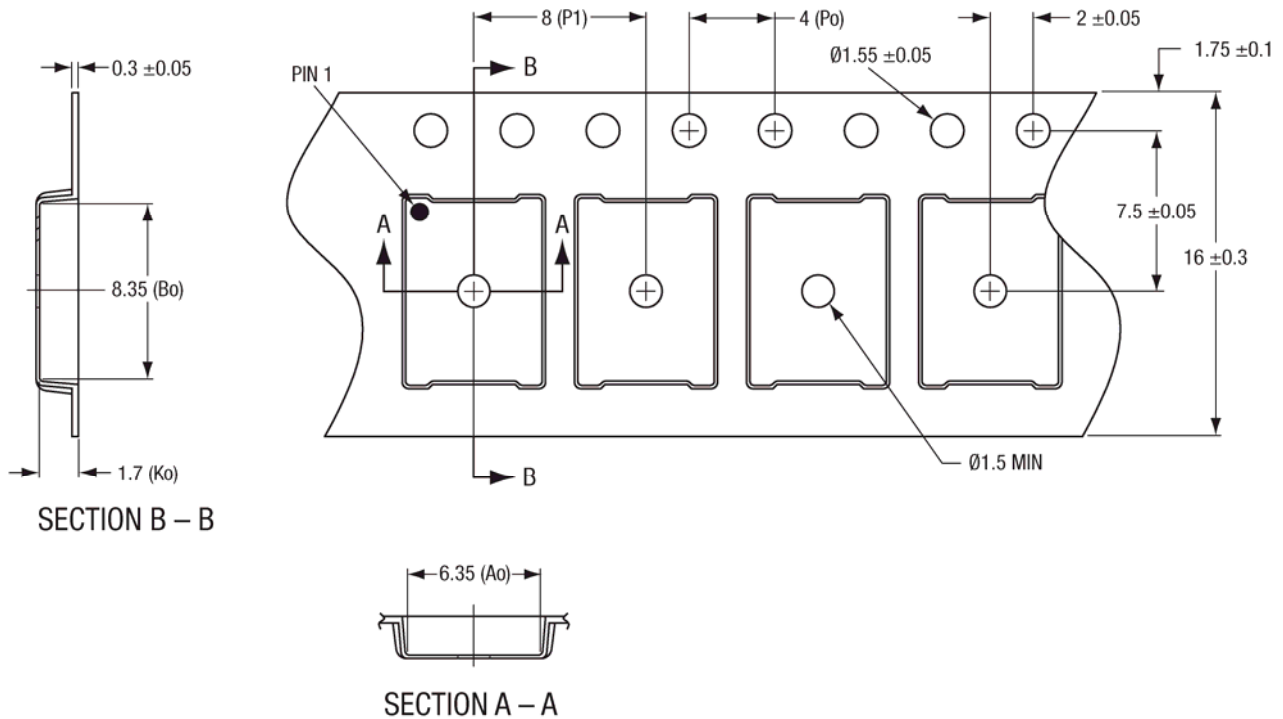
Pad	Name	Description
1	VBATT	Battery input voltage
2	VLOGIC	Control logic level selection/Standby control
3	VRAMP	Analog power control voltage input
4	TX_EN	TX / RX select (mode control)
5	BS	Band Select (mode control)
6	PCS_RX	PCS Receive RF Output (1930-1990 MHz)
7	GSM_RX	GSM Receive RF Output (869-894 MHz)
8	GND	RF and DC Ground
9	GND	RF and DC Ground
10	GND	RF and DC Ground
11	ANT	RF_IN / RF_OUT to Antenna
12	GND	RF and DC Ground
13	GND	RF and DC Ground
14	GND	RF and DC Ground
15	GND	RF and DC Ground
16	GND	RF and DC Ground
17	GSM_IN	RF input 824-849 MHz
18	NC	No Connect
19	PCS_IN	RF input 1850-1910 MHz
20	GND	RF and DC Ground
GND PADS	GROUND GRID	Ground Pads, module underside

Package and Handling Information

Because of its sensitivity to moisture absorption, this device package is baked and vacuum-packed prior to shipment. Instructions on the shipping container label must be followed regarding exposure to moisture after the container seal is broken, otherwise, problems related to moisture absorption may occur when the part is subjected to high temperature during solder assembly.

The SKY77517-21 is capable of withstanding an MSL3/250 °C solder reflow. Care must be taken when attaching this product, whether it is done manually or in a production solder reflow environment. If the part is attached in a reflow oven, the temperature ramp rate should not exceed 3 °C per second; maximum temperature should not exceed 250 °C. If the part is manually attached, precaution should be taken to insure that the part is not subjected to temperatures exceeding 250 °C for more than 10 seconds. For details on attachment techniques, precautions, and handling procedures recommended by Skyworks, please refer to Skyworks Application Note: *PCB Design and SMT Assembly/Rework*, Document Number 101752. Additional information on standard SMT reflow profiles can also be found in the JEDEC *Joint Industry Standard J-STD-020*.

Production quantities of this product are shipped in the standard tape-and-reel format (see Figure 7). For additional packaging details, refer to Skyworks Application Note: *Tape and Reel Information – RF Modules*, Document Number 101568.



NOTES:

1. CARRIER TAPES MUST MEET ALL REQUIREMENTS OF SKYWORKS GP01-D232 PROCUREMENT SPEC FOR TAPE AND REEL SHIPPING.
- ② CARRIER TAPE SHALL BE BLACK CONDUCTIVE POLYSTYRENE.
3. COVER TAPE SHALL BE TRANSPARENT CONDUCTIVE PRESSURE SENSITIVE ADHESIVE (PSA) MATERIAL W/13.3 mm WIDTH.
4. ESD-SURFACE RESISTIVITY SHALL BE $\leq 1 \times 10^{10}$ OHMS/SQUARE PER EIA, JEDEC TNR SPECIFICATION.
5. Po / P1, 10 PITCHES CUMULATIVE TOLERANCE ON TAPE: ± 0.2 mm.
6. Ao & Bo MEASUREMENT POINT TO BE 0.3 mm FROM BOTTOM POCKET.
7. ALL DIMENSIONS ARE IN MILLIMETERS.
8. PART NO.: eC3-MCM0608-16-8-F1-L REV. 0. PLEASE INDICATE ON PURCHASE ORDER.
9. NUMBER OF PARTS per 13 inch (DIAMETER) x 16 mm wide REEL: 2500.

ePAK CARRIER TAPE

CARRIER TAPE OVERMOLD MCM 6 x 8 x 1.4 mm BODY SIZE GP01-D232-081C 101568_019

-Figure 7. Tape and Reel Dimensional Diagram for 6 x 8 x 1.2 mm Package – SKY77517-21 Specific

Electrostatic Discharge Sensitivity

The SKY77517-21 is a Class 1 device. The ESD testing was performed in compliance with JEDEC JESD22-A114B Human Body Model (HBM) and JEDEC JESD22-A115B Machine Model (MM) requirements.

Various failure criteria can be utilized when performing ESD testing. Many vendors employ relaxed ESD failure standards that fail devices only after “the pad fails the electrical specification limits” or “the pad becomes completely non-functional”.

- Personnel Grounding
 - Wrist Straps
 - Conductive Smocks, Gloves and Finger Cots
 - Antistatic ID Badges
- Protective Workstation
 - Dissipative Table Top
 - Protective Test Equipment (Properly Grounded)
 - Grounded Tip Soldering Irons
 - Solder Conductive Suckers
 - Static Sensors
- Facility
 - Relative Humidity Control and Air Ionizers
 - Dissipative Floors (less than $10^9 \Omega$ to GND)
- Protective Packaging and Transportation
 - Bags and Pouches (Faraday Shield)
 - Protective Tote Boxes (Conductive Static Shielding)
 - Protective Trays
 - Grounded Carts
 - Protective Work Order Holders

Skyworks employs stringent criteria, rejecting devices as soon as the pad begins to show any degradation on a curve tracer.

To avoid ESD damage, both latent and visible, it is very important that the product assembly and test areas follow the Class 1 ESD handling precautions listed below.

Ordering Information

Model Number	Manufacturing Part Number	Product Revision	Package	Operating Temperature
SKY77517-21	SKY77517-21		6x8MCM-20	-20 °C to +85 °C

Revision History

Revision	Level	Date	Description
A		November 6, 2007	Initial Issue

References

Application Note: PCB Design and SMT Assembly/Rework, Document Number 101752

Application Note: Tape and Reel Information – RF Modules, Document Number 101568

Application Note: BiCMOS iPAC™ Front-End Module Implementation, Document Number 200576

Application Note: SKY77517 / SKY77518 Evaluation Board Information, Document Number 200574

Standard SMT Reflow Profiles: JEDEC Standard J-STD-020

JEDEC JESD22-A114B Human Body Model (HBM)

JEDEC JESD22-A115B Machine Model (MM)

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课程网址: <http://www.edatop.com/peixun/hfss/11.html>

CST 学习培训课程套装

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课程网址: <http://www.edatop.com/peixun/cst/24.html>



HFSS 天线设计培训课程套装

套装包含 6 门视频课程和 1 本图书,课程从基础讲起,内容由浅入深,理论介绍和实际操作讲解相结合,全面系统的讲解了 HFSS 天线设计的全过程。是国内最全面、最专业的 HFSS 天线设计课程,可以帮助您快速学习掌握如何使用 HFSS 设计天线,让天线设计不再难...

课程网址: <http://www.edatop.com/peixun/hfss/122.html>

13.56MHz NFC/RFID 线圈天线设计培训课程套装

套装包含 4 门视频培训课程,培训将 13.56MHz 线圈天线设计原理和仿真设计实践相结合,全面系统地讲解了 13.56MHz 线圈天线的工作原理、设计方法、设计考量以及使用 HFSS 和 CST 仿真分析线圈天线的具体操作,同时还介绍了 13.56MHz 线圈天线匹配电路的设计和调试。通过该套课程的学习,可以帮助您快速学习掌握 13.56MHz 线圈天线及其匹配电路的原理、设计和调试...

详情浏览: <http://www.edatop.com/peixun/antenna/116.html>



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